


Absolute Maximum Ratings $T_{A}=25^{\circ} \mathrm{C}$ unless othemise noted

| Symbol | Parameter | Ratings | Units |
| :---: | :---: | :---: | :---: |
| $V_{\text {DSs }}$ | Drain-Source Voltage | 20 | V |
| $\mathrm{V}_{\text {Gss }}$ | Gate-Source Voltage | $\pm 12$ | V |
| $\mathrm{I}_{\mathrm{D}}$ | $\begin{aligned} \hline \text { Drain Current } & \text { - Continuous } \\ & \text { - Pulsed } \end{aligned}$ | 4.5 | A |
|  |  | 30 |  |
| $\mathrm{P}_{\mathrm{D}}$ | $\begin{array}{ll}\text { Total Power Dissipation } & \text { (Note 1a) } \\ \text { (Note 1b) }\end{array}$ | 1.0 | W |
|  |  | 0.6 |  |
| $\mathrm{T}_{\mathrm{J},} \mathrm{T}_{\text {stg }}$ | Operating and Storage Junction Temperature Range | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |
| Thermal Characteristics |  |  |  |
| $\mathrm{R}_{\text {өJA }}$ | Thermal Resistance, Junction-to-Ambient (Note 1a) <br> (Note 1b) | 125 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
|  |  | 208 |  |

## Package Marking and Ordering Information

| Device Marking | Device | Reel Size | Tape width | Quantity |
| :---: | :---: | :---: | :---: | :---: |
| $9926 A$ | FDW9926A | $13^{\prime \prime}$ | 12 mm | 2500 units |

## Electrical Characteristics $\quad T_{A}=25^{\circ} \mathrm{C}$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Off Characteristics |  |  |  |  |  |  |
| BV ${ }_{\text {DSs }}$ | Drain-Source Breakdown Voltage | $\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}, \quad \mathrm{I}_{\mathrm{D}}=250 \mu \mathrm{~A}$ | 20 |  |  | V |
| $\Delta \mathrm{BV}$ DSs $\Delta T_{J}$ | Breakdown Voltage Temperature Coefficient | $\mathrm{I}_{\mathrm{D}}=250 \mu \mathrm{~A}$, Referenced to $25^{\circ} \mathrm{C}$ |  | 12 |  | $\mathrm{mV} /{ }^{\circ} \mathrm{C}$ |
| $\mathrm{l}_{\text {dss }}$ | Zero Gate Voltage Drain Current | $\mathrm{V}_{\mathrm{DS}}=16 \mathrm{~V}, \quad \mathrm{~V}_{\mathrm{GS}}=0 \mathrm{~V}$ |  |  | 1 | $\mu \mathrm{A}$ |
| Igss | Gate-Body Leakage | $\mathrm{V}_{\mathrm{GS}}= \pm 12 \mathrm{~V}, \quad \mathrm{~V}_{\mathrm{DS}}=0 \mathrm{~V}$ |  |  | $\pm 100$ | nA |

## On Characteristics (Note 2)

| $\mathrm{V}_{\mathrm{GS}(\mathrm{th})}$ | Gate Threshold Voltage | $\mathrm{V}_{\text {DS }}=\mathrm{V}_{\text {GS }}, \quad \mathrm{I}_{\mathrm{D}}=250 \mu \mathrm{~A}$ | 0.6 | 1.0 | 1.5 | V |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\begin{gathered} \Delta \mathrm{V}_{\mathrm{GS}(\mathrm{th})} \\ \Delta \mathrm{T}_{\mathrm{J}} \end{gathered}$ | Gate Threshold Voltage Temperature Coefficient | $\mathrm{I}_{\mathrm{D}}=250 \mu \mathrm{~A}$, Referenced to $25^{\circ} \mathrm{C}$ |  | -3 |  | $\mathrm{mV} /{ }^{\circ} \mathrm{C}$ |
| $\mathrm{R}_{\mathrm{DS}(\text { (n) }}$ | Static Drain-Source On-Resistance | $\begin{aligned} & \mathrm{V}_{\mathrm{GS}}=4.5 \mathrm{~V}, \quad \mathrm{I}_{\mathrm{D}}=4.5 \mathrm{~A} \\ & \mathrm{~V}_{\mathrm{GS}}=2.5 \mathrm{~V}, \quad \mathrm{I}_{\mathrm{D}}=3.8 \mathrm{~A} \\ & \mathrm{~V}_{\mathrm{GS}}=4.5 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=4.5 \mathrm{~A}, \mathrm{~T}_{\mathrm{J}}=125^{\circ} \mathrm{C} \end{aligned}$ |  | $\begin{aligned} & 24 \\ & 34 \\ & 33 \end{aligned}$ | $\begin{aligned} & 32 \\ & 45 \\ & 48 \end{aligned}$ | $\mathrm{m} \Omega$ |
| $\mathrm{I}_{\text {(on) }}$ | On-State Drain Current | $\mathrm{V}_{\mathrm{GS}}=4.5 \mathrm{~V}, \quad \mathrm{~V}_{\mathrm{DS}}=5 \mathrm{~V}$ | 15 |  |  | A |
| grs | Forward Transconductance | $\mathrm{V}_{\mathrm{DS}}=5 \mathrm{~V}, \quad \mathrm{I}_{\mathrm{D}}=4.5 \mathrm{~A}$ |  | 19 |  | S |

## Dynamic Characteristics

| $\mathrm{C}_{\text {iss }}$ | Input Capacitance | $V_{\text {DS }}=10 \mathrm{~V}, \quad \mathrm{~V}_{\mathrm{GS}}=0 \mathrm{~V}$,$\mathrm{f}=1.0 \mathrm{MHz}$ | 630 | pF |
| :---: | :---: | :---: | :---: | :---: |
| $\mathrm{C}_{\text {oss }}$ | Output Capacitance |  | 150 | pF |
| $\mathrm{C}_{\text {rss }}$ | Reverse Transfer Capacitance |  | 85 | pF |
| $\mathrm{R}_{\mathrm{G}}$ | Gate Resistance | $\mathrm{V}_{\mathrm{GS}}=15 \mathrm{mV}, \mathrm{f}=1.0 \mathrm{MHz}$ | 1.4 | $\Omega$ |

Switching Characteristics (Note 2)

| $\mathrm{t}_{\text {d(on) }}$ | Turn-On Delay Time | $\begin{aligned} & \mathrm{V}_{\mathrm{DD}}=10 \mathrm{~V}, \\ & \mathrm{~V}_{\mathrm{GS}}=4.5 \mathrm{~V}, \end{aligned}$ | $\begin{aligned} & \hline \mathrm{I}_{\mathrm{D}}=1 \mathrm{~A}, \\ & \mathrm{R}_{\mathrm{GEN}}=6 \Omega \end{aligned}$ | 8 | 16 | ns |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{t}_{\mathrm{r}}$ | Turn-On Rise Time |  |  | 8 | 16 | ns |
| $\mathrm{t}_{\text {doff) }}$ | Turn-Off Delay Time |  |  | 15 | 26 | ns |
| $\mathrm{t}_{\mathrm{f}}$ | Turn-Off Fall Time |  |  | 4 | 8 | ns |
| $\mathrm{Q}_{\mathrm{g}}$ | Total Gate Charge | $\begin{aligned} & \mathrm{V}_{\mathrm{DS}}=10 \mathrm{~V}, \\ & \mathrm{~V}_{\mathrm{GS}}=4.5 \mathrm{~V} \end{aligned}$ | $\mathrm{I}_{\mathrm{D}}=4.5 \mathrm{~A}$, | 6.1 | 9 | nC |
| $\mathrm{Q}_{\mathrm{gs}}$ | Gate-Source Charge |  |  | 1.1 |  | nC |
| $\mathrm{Q}_{\mathrm{gd}}$ | Gate-Drain Charge |  |  | 1.8 |  | nC |

Drain-Source Diode Characteristics and Maximum Ratings
$\left.\begin{array}{l|l|l|l|c|c|c}\hline \mathrm{I}_{\mathrm{S}} & \text { Maximum Continuous Drain-Source Diode Forward Current } & & & 0.83 & \mathrm{~A} \\ \hline \mathrm{~V}_{\mathrm{SD}} & \begin{array}{l}\text { Drain-Source Diode Forward } \\ \text { Voltage }\end{array} & \mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}, \quad \mathrm{I}_{\mathrm{S}}=0.83 \mathrm{~A} \quad \text { (Note 2) }\end{array}\right)$

## Notes:

1. $R_{\theta J A}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta J C}$ is guaranteed by design while $R_{\theta C A}$ is determined by the user's board design.
a) $R_{\theta J A}$ is $125^{\circ} \mathrm{C} / \mathrm{W}$ (steady state) when mounted on a 1 inch $^{2}$ copper pad on FR-4.
b) $R_{\theta J A}$ is $208^{\circ} \mathrm{C} / \mathrm{W}$ (steady state) when mounted on a minimum copper pad on FR-4.
2. Pulse Test: Pulse Width < 300 $\mu \mathrm{s}$, Duty Cycle < 2.0\%

## Typical Characteristics



Figure 1. On-Region Characteristics.


Figure 3. On-Resistance Variation with temperature.


Figure 5. Transfer Characteristics.


Figure 2. On-Resistance Variation with Drain Current and Gate voltage.


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

## Typical Characteristics



Figure 7. Gate Charge Characteristics.


Figure 9. Maximum Safe Operating Area.


Figure 8. Capacitance Characteristics.


Figure 10. Single Pulse Maximum Power Dissipation.


Figure 11. Transient Thermal Response Curve.
Thermal characterization performed using the conditions described in Note 1b
Transient thermal response will change depending on the circuit board design.

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